Complementary Power Transistors

DPAK for Surface Mount Applications

Designed for general purpose amplifier and low speed switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Electrically Similar to Popular TIP41 and TIP42 Series
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector–Emitter Voltage	V _{CEO}	100	Vdc
Collector-Base Voltage	V _{CB}	100	Vdc
Emitter-Base Voltage	V _{EB}	5	Vdc
Collector Current – Continuous	I _C	6	Adc
Collector Current – Peak	I _{CM}	10	Adc
Base Current	I _B	2	Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	20 0.16	W W/°C
Total Power Dissipation (Note 1) @ T _A = 25°C Derate above 25°C	P _D	1.75 0.014	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +150	°C
ESD – Human Body Model	HBM	3B	V
ESD – Machine Model	MM	С	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

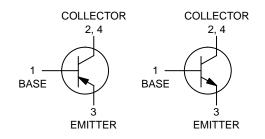


ON Semiconductor®

www.onsemi.com

SILICON POWER TRANSISTORS 6 AMPERES 100 VOLTS, 20 WATTS

COMPLEMENTARY





DPAK CASE 369C STYLE 1

MARKING DIAGRAM



A = Assembly Location

′ = Year

WW = Work Week

J4xC = Device Code x = 1 or 2

G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

These ratings are applicable when surface mounted on the minimum pad sizes recommended.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	6.25	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	71.4	°C/W

^{2.} These ratings are applicable when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

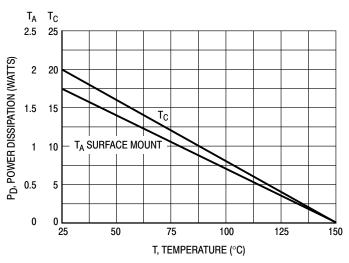
Chavastaviatia	Cumbal	Min	Mey	Unit
Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Sustaining Voltage (Note 3) $(I_C = 30 \text{ mAdc}, I_B = 0)$	V _{CEO(sus)}	100	-	Vdc
Collector Cutoff Current (V _{CE} = 60 Vdc, I _B = 0)	I _{CEO}	-	50	μAdc
Collector Cutoff Current (V _{CE} = 100 Vdc, V _{EB} = 0)	I _{CES}	-	10	μAdc
Emitter Cutoff Current (V _{BE} = 5 Vdc, I _C = 0)	I _{EBO}	-	0.5	mAdc
ON CHARACTERISTICS (Note 3)				•
DC Current Gain $ (I_C = 0.3 \text{ Adc}, V_{CE} = 4 \text{ Vdc}) $ $ (I_C = 3 \text{ Adc}, V_{CE} = 4 \text{ Vdc}) $	h _{FE}	30 15	- 75	_
Collector–Emitter Saturation Voltage (I _C = 6 Adc, I _B = 600 mAdc)	V _{CE(sat)}	-	1.5	Vdc
Base–Emitter On Voltage (I _C = 6 Adc, V _{CE} = 4 Vdc)	V _{BE(on)}	-	2	Vdc
DYNAMIC CHARACTERISTICS	<u> </u>			
Current Gain – Bandwidth Product (Note 4) (I _C = 500 mAdc, V _{CE} = 10 Vdc, f _{test} = 1 MHz)	f _T	3	-	MHz
Small–Signal Current Gain (I _C = 0.5 Adc, V _{CE} = 10 Vdc, f = 1 kHz)	h _{fe}	20	-	_

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

4. $f_T = |h_{fe}| \bullet f_{test}$.

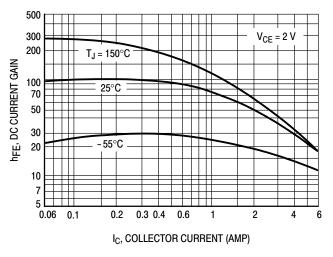
TYPICAL CHARACTERISTICS



 R_B and R_C Varied to obtain desired current levels D_1 MUST be fast recovery type, e.g.: MSB5300 USED ABOVE $I_B\approx 100$ mA MSD6100 USED BELOW $I_B\approx 100$ mA REVERSE ALL POLARITIES FOR PNP.

Figure 1. Power Derating

Figure 2. Switching Time Test Circuit



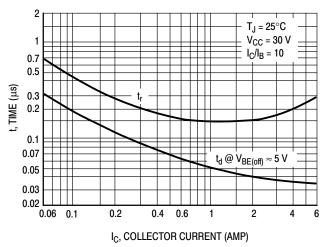
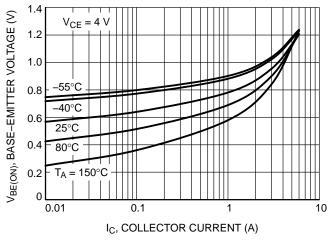


Figure 3. DC Current Gain

Figure 4. Turn-On Time



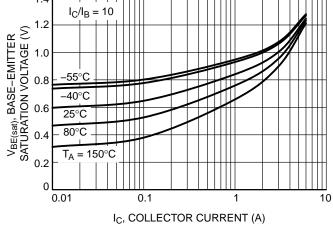


Figure 5. Base Emitter Voltage vs. Collector Current

Figure 6. Base Emitter Saturation Voltage vs.
Collector Current

TYPICAL CHARACTERISTICS

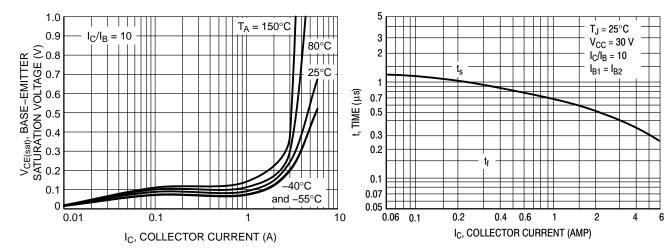


Figure 7. Collector Emitter Saturation Voltage vs. Collector Current

Figure 8. Turn-Off Time

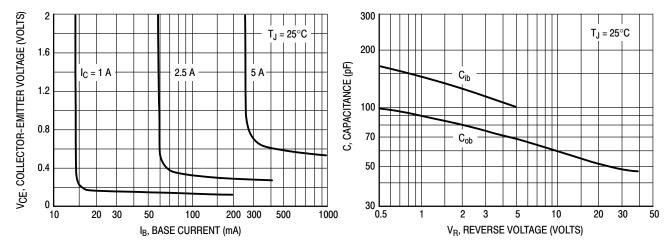


Figure 9. Collector Saturation Region

Figure 10. Capacitance

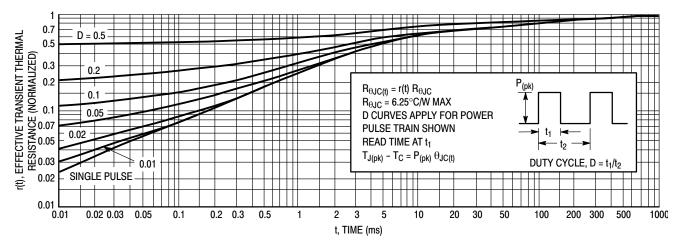


Figure 11. Thermal Response

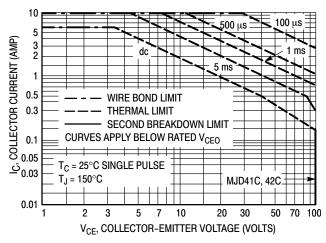


Figure 12. Maximum Forward Bias Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 12 is based on $T_{J(pk)} = 150^{\circ} C$; T_{C} is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^{\circ} C$. $T_{J(pk)}$ may be calculated from the data in Figure 11. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

ORDERING INFORMATION

Device	Package Type	Shipping [†]
NJVMJD41CT4G-VF01*	DPAK (Pb-Free)	2,500 / Tape & Reel
NJVMJD42CT4G-VF01*	DPAK (Pb-Free)	2,500 / Tape & Reel

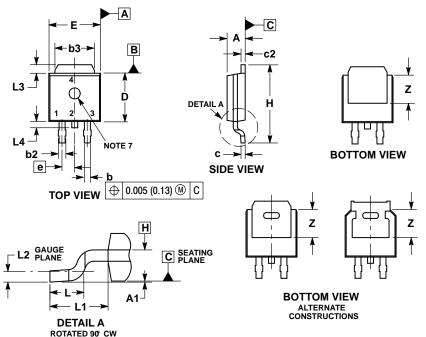
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)

CASE 369C ISSUE F



NOTES

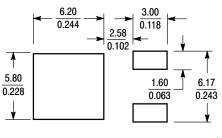
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
- THE CONTROLLING DIMENSION: INCHES.

 THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
- 7. OPTIONAL MOLD FEATURE

	INCHES		MILLIM	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.028	0.045	0.72	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
Е	0.250	0.265	6.35	6.73	
е	0.090 BSC		2.29 BSC		
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.114 REF		2.90 REF		
L2	0.020 BSC		0.51	0.51 BSC	
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

- STYLE 1: PIN 1. BASE
 - 2. COLLECTOR 3. EMITTER
 - COLLECTOR

SOLDERING FOOTPRINT*



mm inches SCALE 3:1

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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